


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	[SEMICONDUCTOR PACKAGE WITH A HEAT SPREADER]		
Application Type : regular, utility Attorney Docket Number : 10230-US-PA			
Correspondence address: Customer Number: 31561 			
Priority Data: Doc.No: 92104001; Country -TW ; Date: 2003-02-26 us-priority-claimed			
Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Sung-Fei Family Name: Wang Residence: City of Residence: Kaohsiung Country of Residence: TW Address-1 of Mailing Address: 1F., No. 21, Alley 90, Lane 729, Chia-Chang, Address-2 of Mailing Address: Nan-Tzu District City of Mailing Address: Kaohsiung State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address: TW Phone: Fax: E-mail:			
Attorney Information: practitioner(s) at Customer Number:			

31561



as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.